

Features

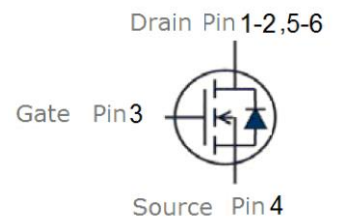
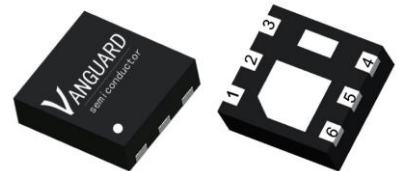
- N-Channel, 2.5V Logic Level Control
- Enhancement mode
- Low on-resistance $R_{DS(on)}$ @ $V_{GS}=2.5\text{ V}$
- Fast Switching
- Pb-free lead plating; RoHS compliant



Halogen-Free

Part ID	Package Type	Marking	Tape and reel information
VS2622AA	DFN2x2	2622	3000PCS/Reel

TDFN2x2



Maximum ratings, at $T_A = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter		Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage		20	V
V_{GS}	Gate-Source voltage		± 12	V
I_S	Diode continuous forward current	$T_C = 25^\circ\text{C}$	45	A
I_D	Continuous drain current @ $V_{GS}=4.5\text{V}$	$T_C = 25^\circ\text{C}$	45	A
		$T_C = 100^\circ\text{C}$	29	A
I_{DM}	Pulse drain current tested ①	$T_C = 25^\circ\text{C}$	180	A
I_{DSM}	Continuous drain current @ $V_{GS}=4.5\text{V}$	$T_A = 25^\circ\text{C}$	13	A
		$T_A = 70^\circ\text{C}$	10	A
P_D	Maximum power dissipation	$T_C = 25^\circ\text{C}$	30	W
P_{DSM}	Maximum power dissipation ②	$T_A = 25^\circ\text{C}$	2.5	W
$T_{STG} T_J$	Storage and Junction Temperature Range		-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	4.1	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	50	$^\circ\text{C/W}$

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ T _j =25°C (unless otherwise stated)						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	20	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =20V,V _{GS} =0V	--	--	1	μA
	Zero Gate Voltage Drain Current(T _j =125°C)	V _{DS} =20V,V _{GS} =0V	--	--	100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±12V,V _{DS} =0V	--	--	±100	nA
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} ,I _D =250μA	0.4	0.7	1	V
R _{DS(ON)}	Drain-Source On-State Resistance ③	V _{GS} =4.5V, I _D =4.5A	--	8.2	11	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance ③	V _{GS} =3.3V, I _D =4A	--	9	12	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance ③	V _{GS} =2.5V, I _D =3A	--	10	14	mΩ
Dynamic Electrical Characteristics @ T _j = 25°C (unless otherwise stated)						
C _{iss}	Input Capacitance	V _{DS} =10V,V _{GS} =0V, f=1MHz	900	1170	1400	pF
C _{oss}	Output Capacitance		100	195	300	pF
C _{rss}	Reverse Transfer Capacitance		80	165	250	pF
R _g	Gate Resistance	f=1MHz	--	2.4	--	Ω
Q _g	Total Gate Charge	V _{DS} =10V,I _D =4.5A, V _{GS} =4.5V	--	15	--	nC
Q _{gs}	Gate-Source Charge		--	6	--	nC
Q _{gd}	Gate-Drain Charge		--	7	--	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} =10V, I _D =4.5A, R _G =3.0Ω, V _{GS} =4.5V	--	3.1	--	nS
t _r	Turn-on Rise Time		--	4.6	--	nS
t _{d(off)}	Turn-Off Delay Time		--	9	--	nS
t _f	Turn-Off Fall Time		--	9.4	--	nS
Source- Drain Diode Characteristics@ T _j = 25°C (unless otherwise stated)						
V _{SD}	Forward on voltage	I _{SD} =4.5A,V _{GS} =0V	--	0.8	1.2	V
t _{rr}	Reverse Recovery Time	T _j =25°C,I _{sd} =4.5A, V _{GS} =0V	--	13	--	nS
Q _{rr}	Reverse Recovery Charge	di/dt=500A/μs		17		nC

NOTE:

- ① Repetitive rating; pulse width limited by max junction temperature.
- ② The power dissipation P_{DSM} is based on R_{θJA} and the maximum allowed junction temperature of 150°C.
- ③ Pulse width ≤ 300μs; duty cycles ≤ 2%.



Typical Characteristics

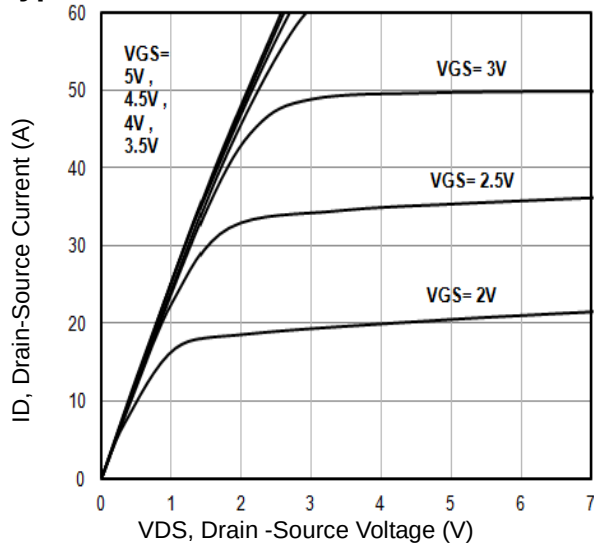


Fig1. Typical Output Characteristics

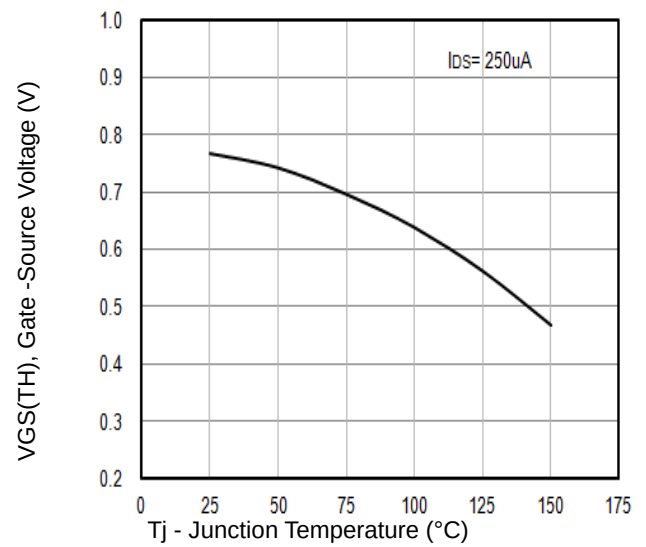


Fig2. $V_{GS(TH)}$ Gate-Source Voltage Vs. T_J

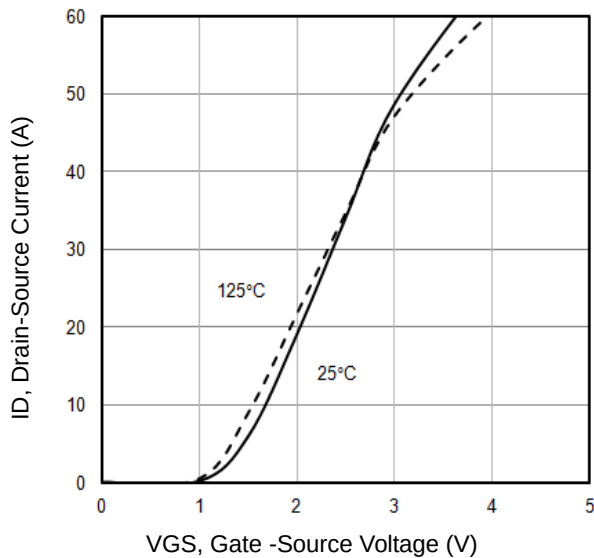


Fig3. Typical Transfer Characteristics

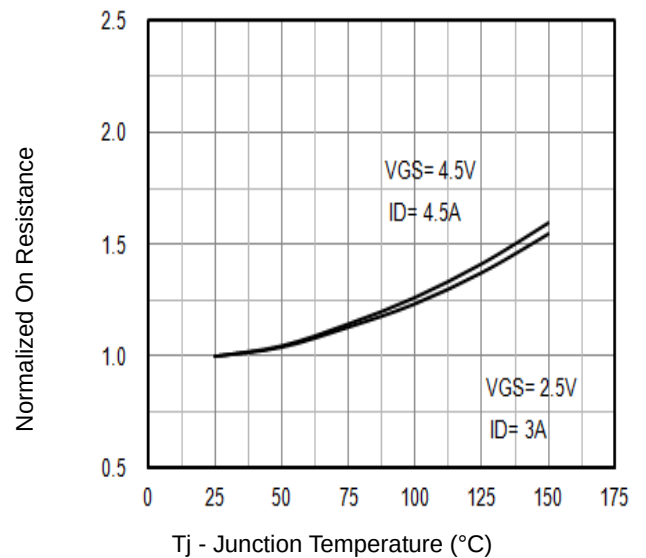


Fig4. Normalized On-Resistance Vs. T_J

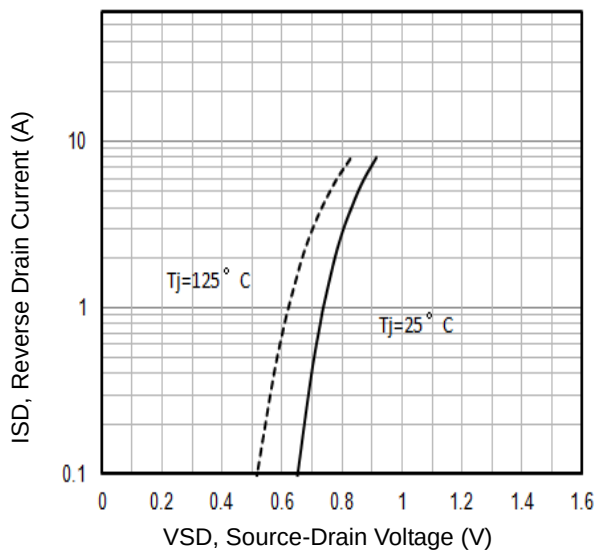


Fig5. Typical Source-Drain Diode Forward Voltage

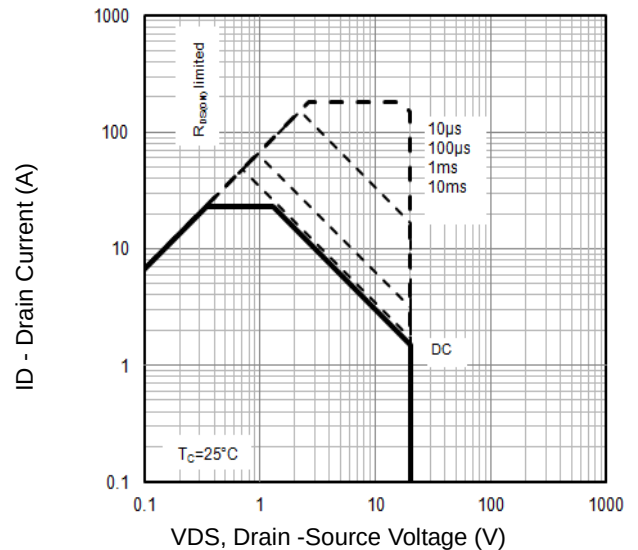


Fig6. Maximum Safe Operating Area

Typical Characteristics

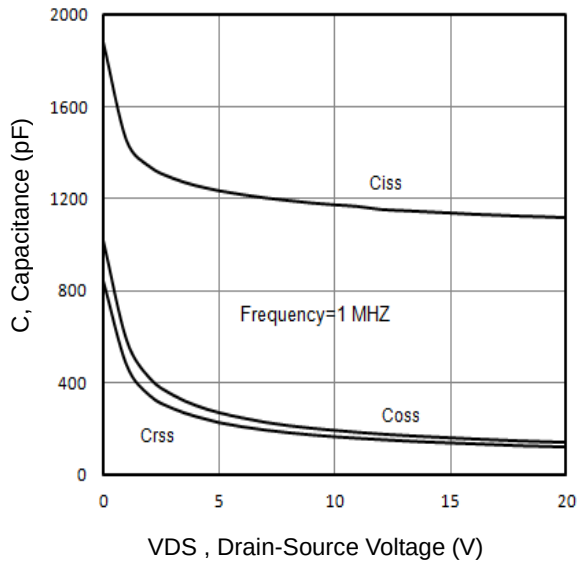


Fig7. Typical Capacitance Vs. Drain-Source Voltage

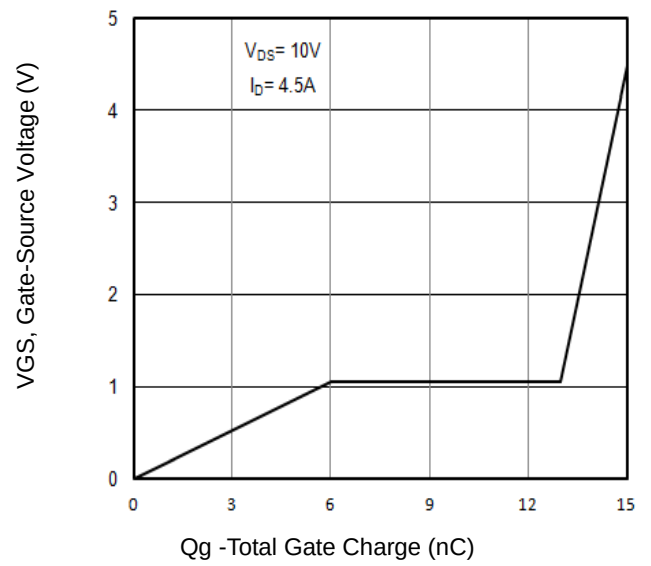


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

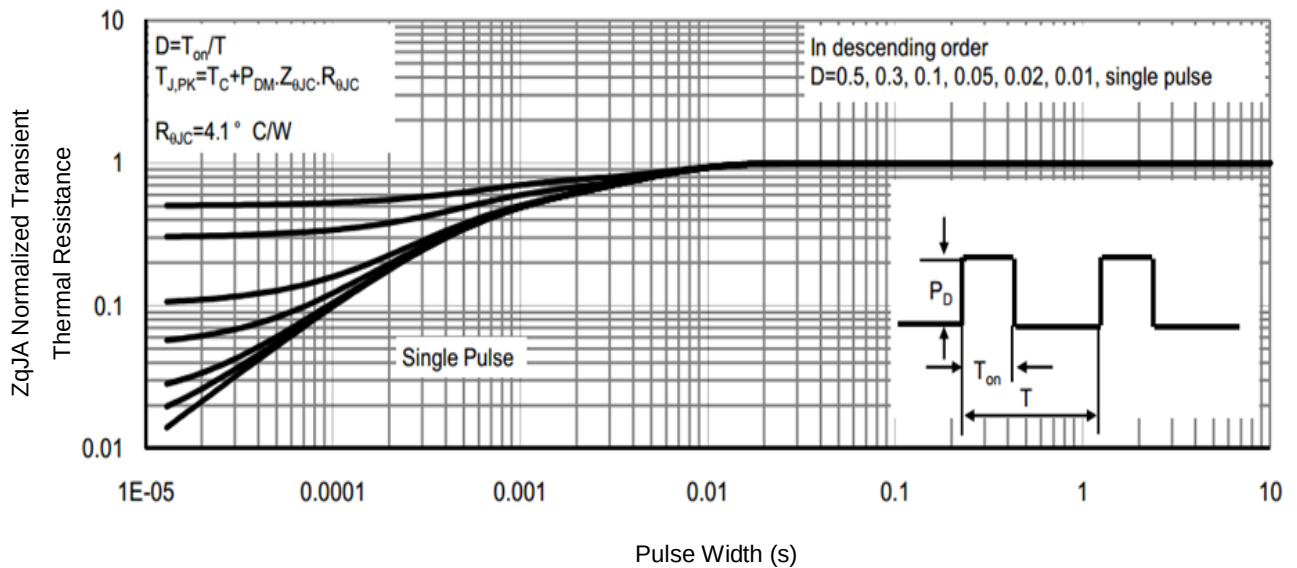


Fig9. Normalized Maximum Transient Thermal Impedance

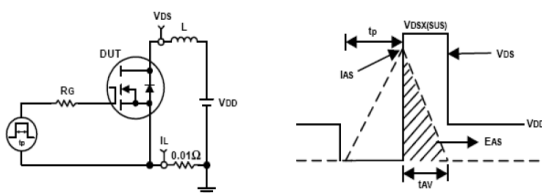


Fig10. Unclamped Inductive Test Circuit and waveforms

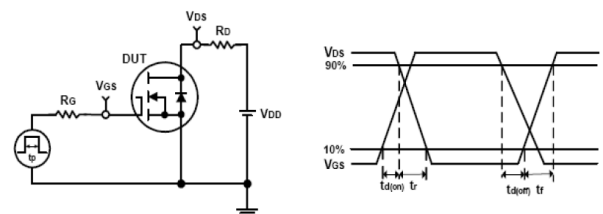
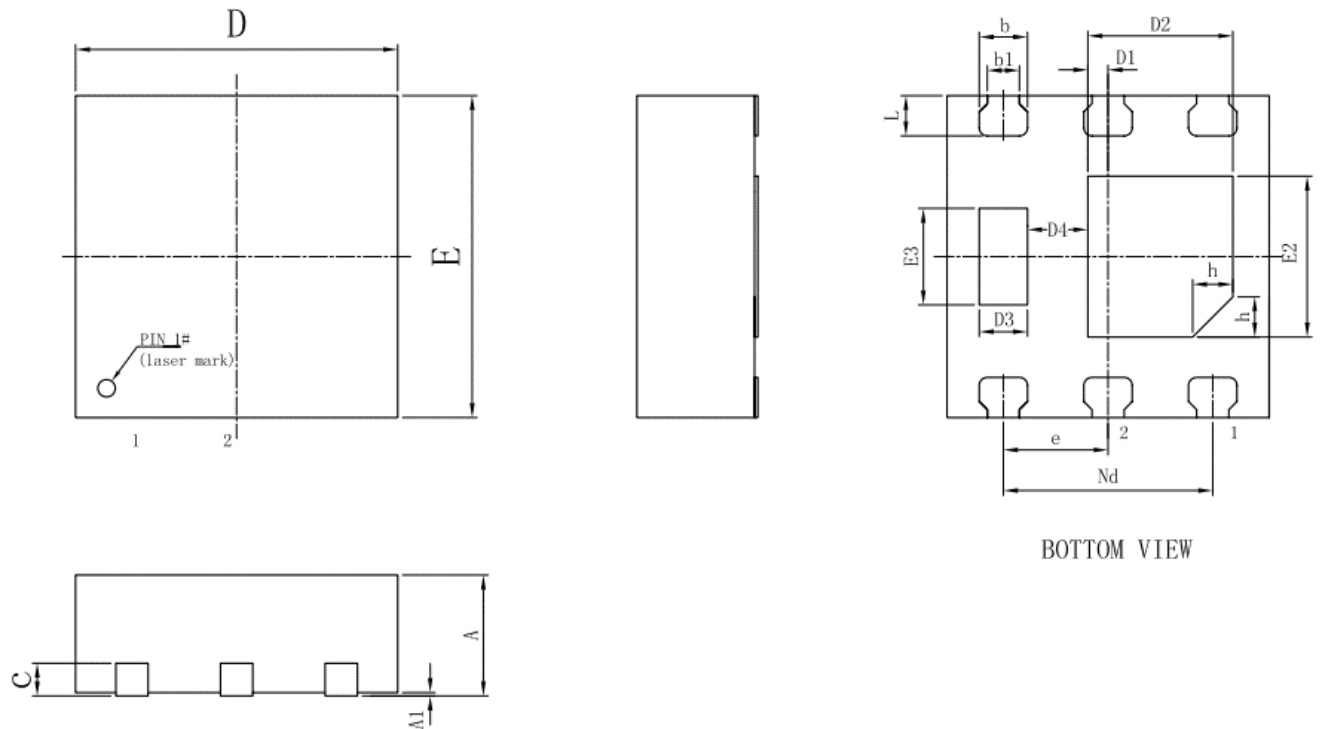


Fig11. Switching Time Test Circuit and waveforms

DFN2x2 Package Outline Data



Symbol	Dimensions (unit: mm)		
	Min	Typ	Max
A	0.70	0.75	0.80
A1	--	0.02	0.05
b	0.25	0.30	0.35
b1	0.20 REF		
c	0.203 REF		
D	1.90	2.00	2.1
D1	0.08	0.125	0.18
D2	0.85	0.90	0.95
D3	0.25	0.3	0.35
D4	0.33	0.375	0.43
e	0.65 BSC		
Nd	1.30 BSC		
E	1.90	2.00	2.10
E2	0.95	1.00	1.05
E3	0.55	0.60	0.65
L	0.20	0.25	0.30
h	0.25 REF		

Customer Service

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